



# **DCR1610F28**

# **Phase Control Thyristor**

Replaces DS5928-1 DS5928-2 January 2024 (LN43058)

### **FEATURES**

- Double Side Cooling
- High Surge Capability

### **APPLICATIONS**

- High Power Drives
- High Voltage Power Supplies
- Static Switches

### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages VDRM and VRRM (V)	Conditions
DCR1610F28 DCR1610F26 DCR1610F24	2800 2600 2400	$T_{Vj} = -40 ^{\circ} C \text{ to } 125 ^{\circ} C,$ $IDRM = IRRM = 100 mA,$ $VDRM, VRRM t_{P} = 10 ms$ $VDSM \& VRSM =$ $VDRM \& VRRM + 100 V$ $respectively$

Lower voltage grades available.

### **KEY PARAMETERS**

$V_{DRM}$	2800V
I <sub>T(AV)</sub>	1610A
Ітѕм	21500A
dV/dt*	1500V/µs
dl/dt	1000A/μs

<sup>\*</sup> Higher dV/dt selections are available on request

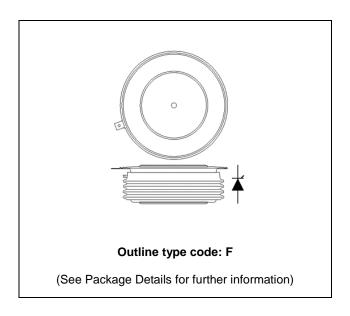


Fig. 1 Package outline

### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

### DCR1610F28

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

www.dynexsemi.com 1/10



## **CURRENT RATINGS**

## T<sub>case</sub> = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Si	de Cooled			
IT(AV)	Mean on-state current	Half wave resistive load	1610	А
IT(RMS)	RMS value	-	2530	Α
lτ	Continuous (direct) on-state current	-	2370	Α

## **SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
Ітѕм	Surge (non-repetitive) on-state current	10ms half sine, Tcase = 125°C	21.5	kA
l²t	I2t for fusing	V <sub>R</sub> = 0	2.31	MA <sup>2</sup> s

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
		Double side cooled	DC	-	18.3	°C/kW
Rth(j-c)	Thermal resistance - junction to case	Cingle side socied	Anode DC	-	33.3	°C/kW
		Single side cooled	Cathode DC	-	41.7	°C/kW
D	Thermal resistance - case to heatsink	Clamping force 23kN	Double side	-	4.0	°C/kW
Rth(c-h)		(with mounting compound)	Single side	-	8.0	°C/kW
Tvj	Virtual junction temperature	Blocking Vdrm / Vrrm		-	125	°C
Tstg	Storage temperature range			-55	125	°C
Fm	Clamping force		20	25	kN	

www.dynexsemi.com 2/10



## **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Condition	ns	Min.	Max.	Units
IRRM/IDRM	Peak reverse and off-state current	At VRRM/VDRM, Tcase = 125°C		-	100	mA
Vтм	Instantaneous forward voltage	At 2900A peak, Tj = 25°C		1.45	1.53	V
dV/dt	Max. linear rate of rise of off-state voltage	To 67% VdRM, Tj = 125°C, ga	ate open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% V <sub>DRM</sub> to 2x I <sub>T(AV)</sub> Repetitive 50Hz		-	250	A/µs
di/dt	Trate of fise of off-state current	tr < 0.5µs, Tj = 125°C	Non-repetitive	-	1000	A/µs
Varia	Threshold voltage - Low level	300A to 1200A at Tcase = 125°C 1200A to 4000A at Tcase = 125°C		-	0.79	V
<b>V</b> т(то)	Threshold voltage - High level			-	0.92	V
_	On-state slope resistance - Low level	300A to 1200A at Tcase = 125°C		-	0.35	mΩ
ľΤ	On-state slope resistance - High level	1200A to 4000A at Tcase = 1	25°C	-	0.24	mΩ
tgd	Delay time	$V_D = 67\% \ V_{DRM}$ , gate source 30V, $10\Omega$ $t_T = 0.5 \mu s$ , $T_j = 25 ^{\circ} C$		1	3	μs
tq	Turn-off time	T <sub>j</sub> = 125°C, V <sub>R</sub> = 100V, dI/dt = 5A/μs, dV <sub>DR</sub> /dt = 20V/μs linear to 2500V		-	600	μs
Qs	Stored charge	$I_T = 1000A$ , $t_P = 1000\mu s$ , $T_J = 125$ °C, $dI/dt = 5A/\mu s$ . [LEM]		2500	3500	μC
IRR	Reverse recovery current			100	125	А
IL	Latching current	Tj = 25°C, VD = 5V		-	3	А
lн	Holding current	$T_j = 25$ °C, $R_{G-K} = \infty$ , $I_{TM} = 50$	0A, I⊤ = 5A	-	300	mA

www.dynexsemi.com 3/10



### **GATE TRIGGER CHARACTERISTICS AND RATINGS**

Symbol Parameter		Test Conditions	Max.	Units
<b>V</b> GT	Gate trigger voltage	VDRM = 5V, Tcase = 25°C	1.5	V
V <sub>GD</sub> Gate non-trigger voltage At		At 50% VDRM, Tcase = 125°C	0.4	V
lgт	Iст Gate trigger current VDRM = 5V, Tcase = 25°C		250	mA
IGD	lgb Gate non-trigger current At 50% Vdrm, Tcase = 125°C		10	mA

### **CURVES**

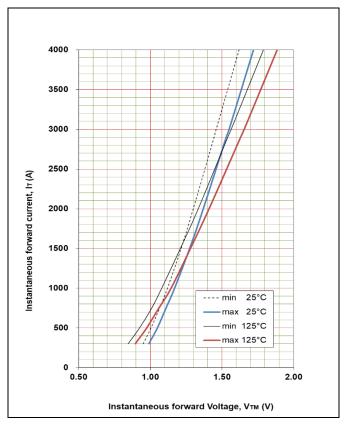


Fig. 2 Maximum & minimum on state characteristics

## **VTM EQUATION**

 $V_{TM} = A + B.ln(I_T) + C.I_T + D.\sqrt{I_T}$ 

Where A = 0.592874

B = 0.022973

C = 0.000164

D = 0.007034

These values are valid for  $T_j = 125$ °C for  $I_T 300A$  to 4000A

www.dynexsemi.com 4/10



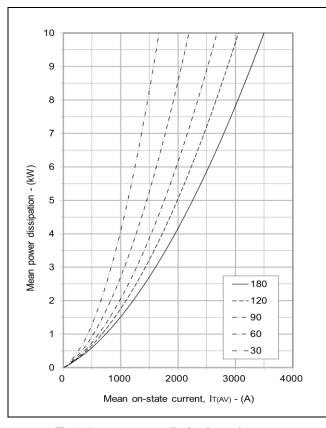


Fig. 3 On-state power dissipation - sine wave

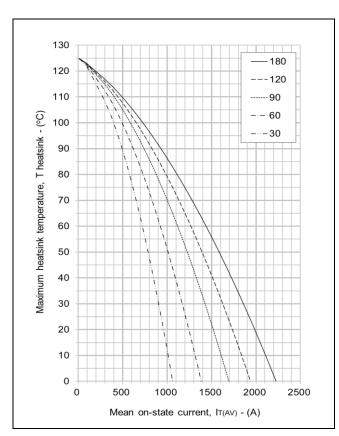


Fig. 5 Maximum permissible heatsink temperature, double side cooled - sine wave

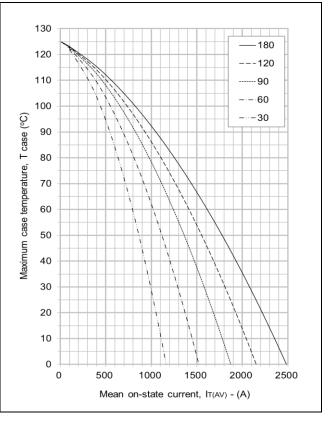


Fig. 4 Maximum permissible case temperature, double side cooled - sine wave

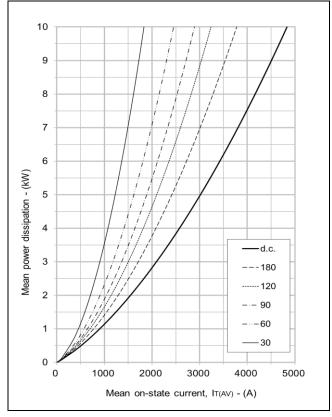


Fig. 6 On-state power dissipation - rectangular wave

www.dynexsemi.com 5/10



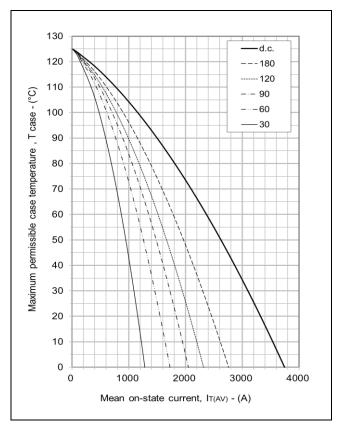
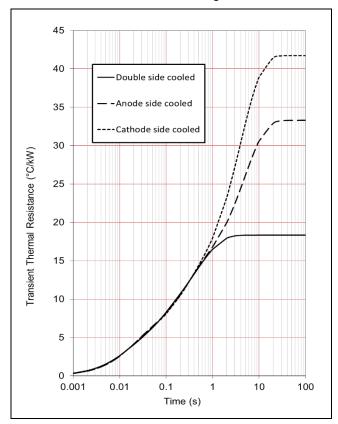


Fig. 7 Maximum permissible case temperature, double side cooled - rectangular wave



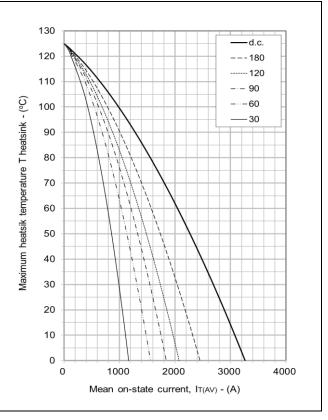


Fig. 8 Maximum permissible heatsink temperature, double side cooled - rectangular wave

		1	2	3	4
Double side	Ri(°C/kW)	7.561	4.077	3.842	2.867
cooled	Ti(s)	0.688	0.254	0.061	0.010
Anode side	Ri(°C/kW)	11.556	8.581	4.794	8.364
cooled	Ti(s) 4.222 6.027	6.027	0.017	0.226	
Cathode side	Ri(°C/kW)	6.721	4.622	15.539	14.863
cooled	Ti(s)	0.191	0.016	5.001	3.317

$$Z_{th} = \sum_{i=1}^{i=4} R_i \cdot \left(1 - \exp\left(-\frac{T}{T_i}\right)\right)$$

 $\Delta R_{\text{th(j-c)}}$  Conduction

Tables show the increments of thermal resistance R  $_{\text{th(j-c)}}$  when the device operates at conduction angles other than d.c.

	Double side cooling						
	∆Z <sub>th</sub> (	(z)					
θ°	sine.	rect.					
180	3.19	2.14					
120	3.72	3.10					
90	4.29	3.64					
60	4.81	4.23					
30	5.22	4.88					
15	5.40	5.22					

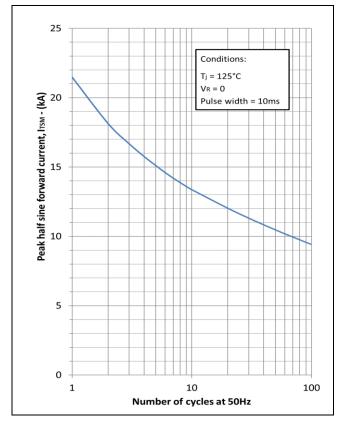
		Anode Side Cooling				
		ΔZ,	<sub>h</sub> (z)			
	θ°	sine.	rect.			
	180	2.97 2.03				
	120	3.43	289			
	90	3.92	3.36			
	60	4.36 3.87				
Ī	30	4.69 4.41				
	45	4.04	470			

-	Anode Side Cooling			Anode Side Cooling Cathode Sided Coolin			d Cooling
	$\Delta Z_{th}(z)$				$\Delta Z_{t}$	<sub>h</sub> (z)	
θ°	sine.	rect.		θ°	sine.	rect.	
180	2.97	203		180	295	2.02	
120	3.43	289		120	3.40	2.87	
90	3.92	3.36		90	3.88	3.34	
60	4.36	3.87		60	4.31	3.84	
30	4.69	4.41		30	4.64	4.37	
15	4.84	4.70		15	4.79	4.65	

Fig. 9 Maximum (limit) transient thermal impedance - junction to case (degC/kW)

www.dynexsemi.com 6/10





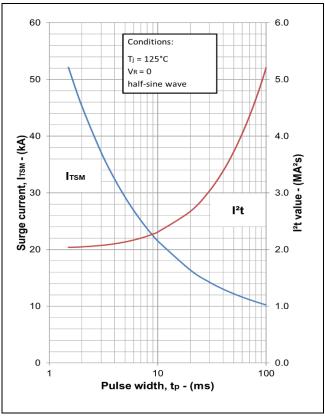


Fig. 10 Multi-cycle surge current

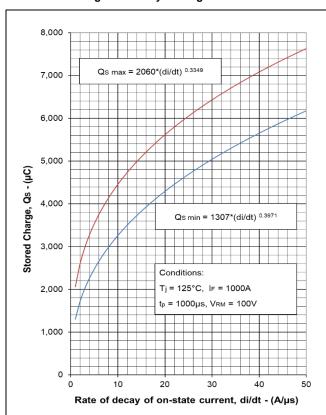


Fig. 12 Stored charge

Fig. 11 Single-cycle surge current

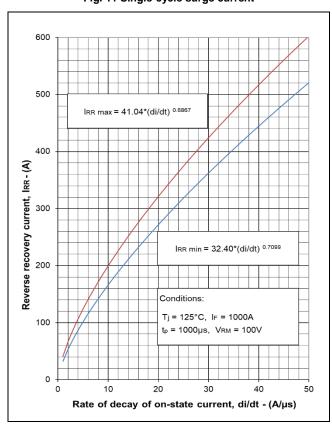


Fig. 13 Reverse recovery current

www.dynexsemi.com 7/10



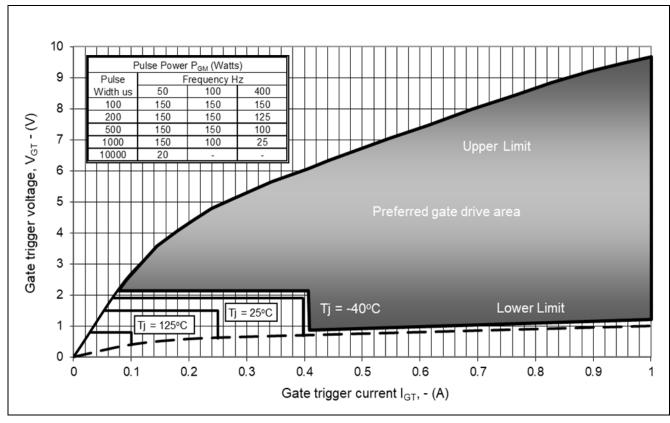


Fig. 14 Gate characteristics

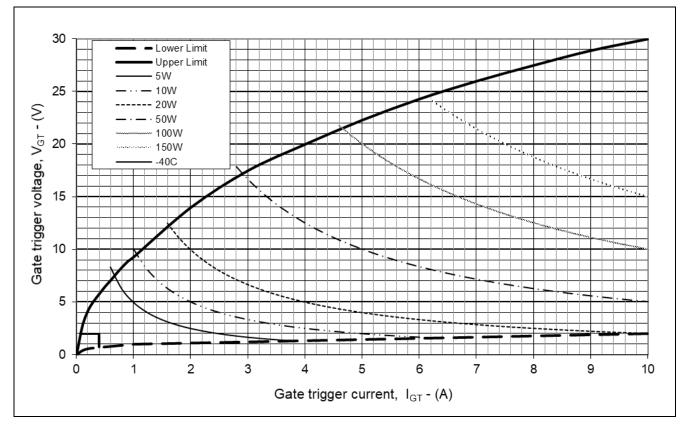


Fig. 15 Gate characteristics

www.dynexsemi.com 8/10



### **PACKAGE DETAILS**

For further package information, please contact Customer services.

All dimensions in mm, unless stated otherwise.

### DO NOT SCALE

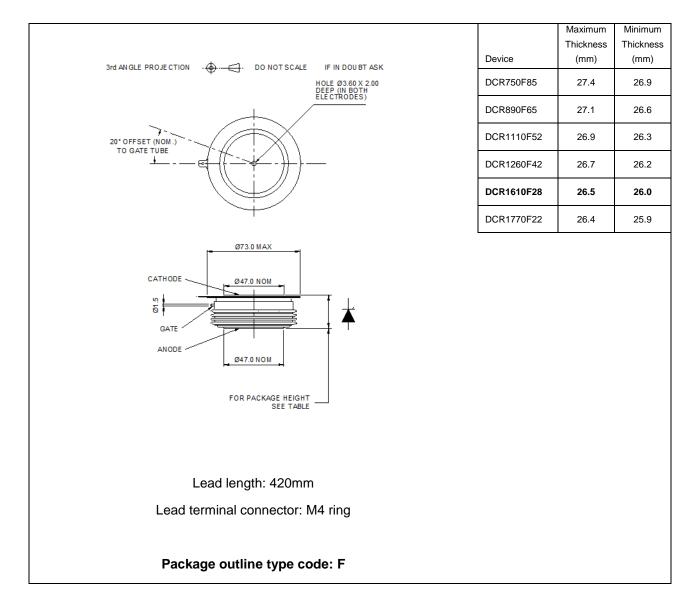


Fig. 16 Package outline

www.dynexsemi.com 9/10



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www.dynexsemi.com 10/10